

TIC116A, TIC116B, TIC116C, TIC116D, TIC116E, TIC116M, TIC116N, TIC116S

P-N-P-N SILICON REVERSE-BLOCKING TRIODE THYRISTORS

- 8 A Continuous On-State Current
- 80 A Surge-Current
- Glass Passivated Wafer
- 100 V to 800 V Off-State Voltage
- Max I_{GT} of 20 mA
- Compliance to ROHS

ABSOLUTE MAXIMUM RATINGS

Symbol	Ratings	Value								Unit
Cymbol	Ratings		В	С	D	E	М	S	N	
V _{DRM}	Repetitive peak off-state voltage (see Note1)		200	300	400	500	600	700	800	V
V _{RRM}	Repetitive peak reverse voltage	100	200	300	400	500	600	700	800	V
I _{T(RMS)}	Continuous on-state current at (or below) 70°C case temperature (see note2)	8					Α			
I _{T(AV)}	Average on-state current (180° conduction angle) at(or below) 70°C case temperature (see Note3) 5				Α					
I _{TM}	Surge on-state current (see Note4)	80				Α				
I _{GM}	Peak positive gate current (pulse width ≤300 µs)		3							Α
P _{GM}	Peak power dissipation (pulse width ≤300 µs)		5							W
P _{G(AV)}	Average gate power dissipation (see Note5)		1							W
T _C	Operating case temperature range		-40 to +110							°C
T _{stg}	Storage temperature range		-40 to +125							°C
TL	Lead temperature 1.6 mm from case for 10 seconds		230						°C	



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THERMAL CHARACTERISTICS

Symbol	ı	Value	Unit	
t _{gt}	Gate-controlled Turn-on time	$V_{AA} = 30 \text{ V}, R_L = 6$, $R_{GK(eff)} = 100$, $V_{in} = 20 \text{ V}$	0.8	
tq	Circuit-communicated Turn-off time	$V_{AA} = 30 \text{ V}, R_{L} = 6 , I_{RM} \approx 10 \text{ A}$	11	μs
R _{∂JC}	Junction to case thermal re	≤ 3	°C/W	
R _{∂JA}	Junction to free air thermal	≤ 62.5		

ELECTRICAL CHARACTERISTICS

TC=25°C unless otherwise noted

Symbol	Ratings	Test Condition(s)	Min	Тур	Max	Unit
I _{DRM}	Repetitive peak off-state current	V_D = Rated V_{DRM} , R_{GK} = 1 k Ω T_C = 110°C	-	-	2	mA
I _{RRM}	Repetitive peak reverse current	V_R = Rated V_{RRM} , I_G = 0 T_C = 110°C	-	-	2	mA
I _{GT}	Gate trigger current	V_{AA} = 6 V, R _L = 100 Ω $t_{p(g)} \ge 20 \mu s$	-	5	20	mA
		V_{AA} = 6 V, R _L = 100 Ω R _{GK} = 1 kΩ, t _{p(g)} ≥ 20μs T _C = -40°C	-	-	2.5	
V_{GT}	Gate trigger voltage	V_{AA} = 6 V, R_L = 100 Ω R_{GK} = 1 kΩ, $t_{p(g)}$ ≥ 20μs	-	0.8	1.5	V
		V_{AA} = 6 V, R _L = 100 Ω R _{GK} = 1 kΩ, t _{p(g)} ≥ 20μs T _C = 110°C	0.2	-	-	
	Holding current	V_{AA} = 6 V, R_{GK} = 1 k Ω initiating I_T = 100 mA	-	-	40	
I _H	Tribianing current	V_{AA} = 6 V, R_{GK} = 1 kΩ initiating I_T = 100 mA T_C = -40°C	-	-	70	mA
V_{TM}	Peak on-state voltage	I _{TM} = 8A (see Note6)	-	-	1.7	V
dv/dt	Critical rate of rise of off- state voltage	V_D = Rated V_D T_C = 110°C	-	100	-	V/µs



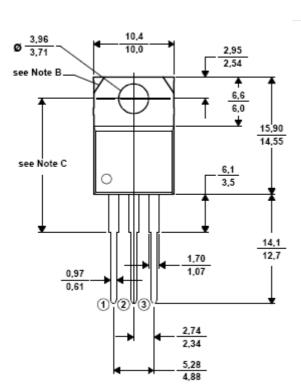
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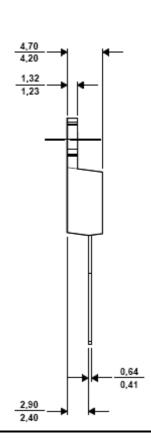
Notes:

- 1. These values apply when the gate-cathode resistance R_{GK} = $1k\Omega$
- 2. These values apply for continuous dc operation with resistive load. Above 70°C derate linearly to zero at 110°C.
- 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 70°C derate linearly to zero at 110°C.
- 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
- 5. This value applies for a maximum averaging time of 20 ms.
 6. This parameters must be measured using pulse techniques, t_W = 300µs, duty cycle ≤ 2 %, voltage-sensing contacts, separate from the courrent-carrying contacts, are located within 3.2mm (1/8 inch) from de device body

MECHANICAL DATA CASE TO-220

TO220

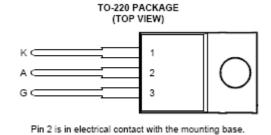






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PINNING



Pin 1 :	kathode
Pin 2 :	Anode
Pin 3 :	Gate

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info@comsetsemi.com